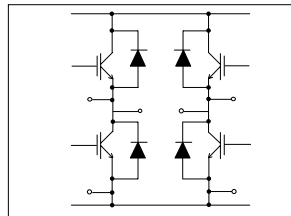


Features

- Gen. 4 Warp Speed IGBT Technology
- HEXFRED™ Antiparallel Diodes with UltraSoft Reverse Recovery
- Very Low Conduction and Switching Losses
- Optional SMT Thermystor Inside
- Aluminum Nitride DBC
- Very Low Stray Inductance Design for High Speed Operation



$$V_{CES} = 600V$$

$$V_{CE(on) \text{ typ.}} = 2.2V @$$

$$V_{GE} = 15V, I_C = 25A$$

$$T_C = 25^\circ C$$

Benefits

- Optimized for Welding, UPS and SMPS Applications
- Operating Frequencies > 20 kHz Hard Switching, >200 kHz Resonant Mode
- Low EMI, requires Less Snubbing
- Direct Mounting to Heatsink
- PCB Solderable Terminals
- Very Low Junction-to-Case Thermal Resistance

Absolute Maximum Ratings

Parameters		Max	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
I_C	Continuos Collector Current	@ $T_C = 25^\circ C$	50
		@ $T_C = 100^\circ C$	25
I_{CM}	Pulsed Collector Current	200	
I_{LM}	Peak Switching Current	200	
I_F	Diode Continuous Forward Current	@ $T_C = 100^\circ C$	25
I_{FM}	Peak Diode Forward Current	200	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
V_{ISOL}	RMS Isolation Voltage, Any Terminal to Case, $t = 1 \text{ min}$	2500	
P_D	Maximum Power Dissipation	@ $T_C = 25^\circ C$	900
		@ $T_C = 100^\circ C$	400

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
V _{(BR)CES} Collector-to-Emitter Breakdown Voltage	600			V	V _{GE} = 0V, I _C = 250μA
V _{CE(on)} Collector-to-Emitter Voltage		1.85			V _{GE} = 15V, I _C = 25A
		1.7			V _{GE} = 15V, I _C = 25A, T _J = 150°C
V _{GE(th)} Gate Threshold Voltage	3		6		I _C = 250μA
ΔV _{GE(th)} /ΔT _J Temperature Coeff. of Threshold Voltage		-		mV/°C	V _{GE} = V _{CE} , I _C = 500μA
g _{fe} Forward Transconductance		40		S	V _{CE} = 100V, I _C = 25A
I _{CES} Collector-to-Emitter Leaking Current			250	μA	V _{GE} = 0V, V _{CE} = 600V
			5000		V _{GE} = 0V, V _{CE} = 600V, T _J = 150°C
V _{FM} Diode Forward Voltage Drop		1.3		V	I _F = 25A, V _{GE} = 0V
		1.2			I _F = 25A, V _{GE} = 0V, T _J = 150°C
I _{GES} Gate-to-Emitter Leakage Current			± 100	nA	V _{GE} = ± 20V

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
Q _g Total Gate Charge (turn-on)		180		nC	I _C = 25A
Q _{ge} Gate-Emitter Charge (turn-on)		25			V _{CC} = 400V
Q _{gc} Gate-Collector Charge (turn-on)		63			V _{GE} = 15V
E _{on} Turn-On Switching Loss		950		μJ	R _{g1} = R _{g2} = 5Ω, I _C = 25A
E _{off(1)} Turn-Off Switching Loss		320			V _{CC} = 480V
E _{ts(1)} Total Switching Loss		1270			V _{GE} = ±15V
C _{ies} Input Capacitance		4000		pF	V _{GE} = 0V
C _{oes} Output Capacitance		260			V _{CC} = 30V
C _{res} Reverse Transfer Capacitance		68			f = 1.0 MHz
t _{rr} Diode Reverse Recovery Time		50		ns	V _R = 200V, I _C = 25A
I _{rr} Diode Peak Reverse Current		4.5		A	di/dt = 200A/μs
Q _{rr} Diode Recovery Charge		112		nC	
di _(rec) /dt Diode Peak Rate of Fall of Recovery During t _b		250		A/μs	

Thermal- Mechanical Specifications

Parameters	Min	Typ	Max	Units
T _J Operating Junction Temperature Range	- 40		150	°C
T _{STG} Storage Temperature Range	- 40		125	
R _{thJC} Junction-to-Case	IGBT		0.7	°C/ W
	Diode		0.9	
R _{thCS} Case-to-Sink (Heatsink Compound Thermal Conductivity = 1 W/mK)	Module	0.06		
Weight		66		g

